

ABSTRACT OF THE DISCLOSURE

A transformable pressure sensitive adhesive composition comprised of from about 15 to about 80% by weight of a polymer having a softening point greater than 60 °C; from about 20 to about 85% by weight of a polymerizable resin having a softening point less than 30 °C; a latent initiator in an amount sufficient to cause a reaction between said polymer and said resin; and optionally, a crosslinking agent. The transformable pressure sensitive adhesive has particular applicability in connection with organic light emitting diode display devices, light emitting diode display devices, medical diagnostic testing devices, flexible or rigid LCD display devices, plasma display devices, and electrochromic devices.